

Part Number: XZMD55W

3.2x1.6mm SMD CHIP LED LAMP



Features

- •3.2mmx1.6mm SMT LED, 1.1mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- $\bullet PACKAGE: 2000PCS \ / \ REEL.$
- •MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- •Rohs Compliant.

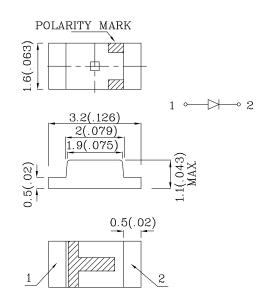




Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.2(0.008") unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Rati (TA=25°C)	MD (InGaAlP)	Unit	
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	185	mA
Power Dissipation	Рт	75	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	



Operating Characteristic (TA=25°C)	MD (InGaAlP)	Unit	
Forward Voltage (Typ.) (IF=20mA)	VF	1.9	V
Forward Voltage (Max.) (IF=20mA)	VF	2.5	V
Reverse Current (Max.) (VR=5V)	Ir	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λΡ	640	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λ D	628	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	27	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	45	pF

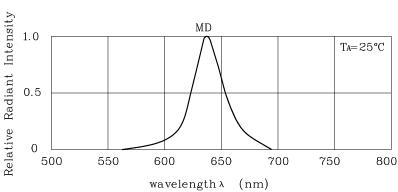
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 0 1/2
				min.	typ.		
XZMD55W	Red	InGaAlP	Water Clear	70	198	640	120°
Published Date :	JAN 23, 2008	Drawii	ng No :XDSA1298	V5	Checked	d : B.L.LIU	P.1/4



Part Number: XZMD55W

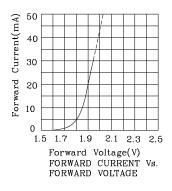
3.2x1.6mm SMD CHIP LED LAMP

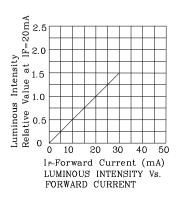


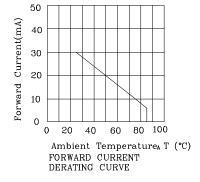


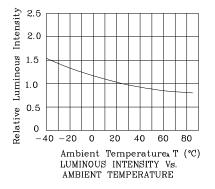
RELATIVE INTENSITY Vs. WAVELENGTH

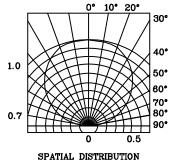
❖ MD









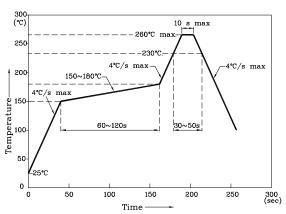




Part Number: XZMD55W

3.2x1.6mm SMD CHIP LED LAMP

Reflow Soldering Profile For Lead-free SMT Process.

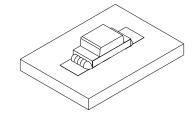


NOTES:

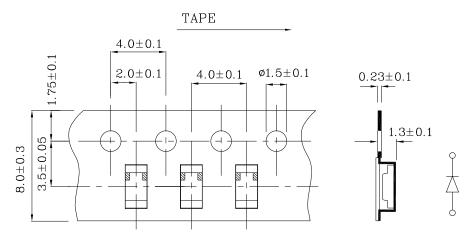
- 1. Maximum soldering temperature should not exceed 260°c.
- 2. Recommended reflow temperature: 145°c-260°c.
- 3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units: mm;Tolerance:± 0.1)

- 1.75 2.0 1.75
- ❖ The device has a single mounting surface. The device must be mounted according to the specifications.



* Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: \pm -0.1V

Note: Accuracy may depend on the sorting parameters. $\,$



Part Number:

3.2x1.6mm SMD CHIP LED LAMP

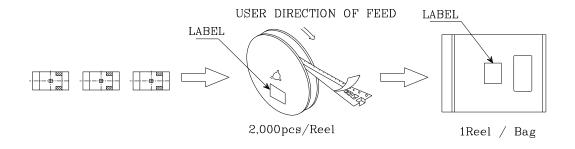
XZMD55W

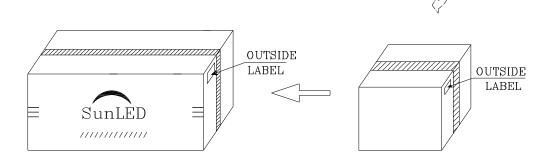
PACKING & LABEL SPECIFICATIONS

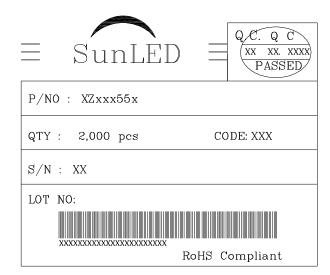
60K/ BOX

XZMD55W

30K/ Box







Published Date: JAN 23, 2008 V_5 Checked: B.L.LIU P.4/4 Drawing No :XDSA1298